Cellular structured Cu$_2$Sn$_{0.8}$Co$_{0.2}$S$_3$ with enhanced thermoelectric performance realized by liquid-phase sintering

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Figure S1. XRD patterns for both powder and bulk Cu$_{2}$Sn$_{0.8}$Co$_{0.2}$S$_{3}$-0.05Sn samples.

Figure S2. Field emission scanning electron microscopy (FE-SEM) images for the fracture surface of (a, b) Cu$_{2}$Sn$_{0.8}$Co$_{0.2}$S$_{3}$ and (c, d) Cu$_{2}$Sn$_{0.8}$Co$_{0.2}$S$_{3}$-0.05Sn.
Figure S3. Cycle test for temperature dependent (a) electrical conductivity, (b) Seebeck coefficient and (c) power factor of $\text{Cu}_2\text{Sn}_{0.8}\text{Co}_{0.2}\text{S}_3-0.05\text{Sn}$. 